

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3267	substrate and land and (chip or die) and bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/08/17 15:07
L2	1197	1 and (warp\$ or bend or bending or bended)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/08/17 15:09